



04-10-00

\$GP 2812

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Cabuz et al.

Serial No.: 09/749,171

Examiner: Simkovic, Viktor

Filed: December 27, 2000

Group Art Unit: 2812

For: THIN SILICON MICROMACHINED STRUCTURES

Docket No.: 1100.1116101 (H16-26635)

TRANSMITTAL SHEET

Box Amendment

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

CERTIFICATE UNDER 37 C.F.R. 1.10: The undersigned hereby certifies that this paper or papers, as described herein, are being deposited in the United States Postal Service, "Express Mail Post Office to Addressee" having an Express Mail mailing label number of EL799292249US, in an envelope addressed to: Box Amendment, Assistant Commissioner for Patents, Washington, D.C., 20231 on this 9th day of April, 2002.

By Lynn Thompson
Lynn Thompson

We are transmitting herewith the attached:

☒ Amendment

☐ No additional fee required

☒ The fee has been calculated as shown:

CLAIMS AS AMENDED							
	(3)	(4)	(5)	SMALL ENTITY		OTHER	
	REMAINING CLAIMS	HIGHEST PAID	EXTRA	RATE	ADD'L FEE	RATE	ADD'L FEE
TOTAL CLAIMS	24-20	0=	4	x9=	\$	x18=	\$72
INDEPENDENT CLAIMS	7-3	0=	4	x42=	\$	x84=	\$ 336
() FIRST MULTIPLE DEPENDENT CLAIM				+140=	\$	+280=	\$
TOTAL				\$		\$408.00	

[]

A check in the amount of \$ 408.00 is enclosed.

[X]

Please charge any deficiencies or credit any overpayment in the enclosed fees to
Deposit Account No. 50-0413.

By: 

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PATENT

#5/A
186
4-18-02

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By Lynn Thompson
Lynn Thompson

Dear Sir:

In response to the Office Action dated January 16, 2002, please amend the above-captioned patent application as follows:

In the Title

Please change the title to read --THIN MICROMACHINED STRUCTURES--.

In the Claims

Please add newly presented claims 20-23.

Please amend claims 1, 14, and 19 as follows:

1. (Amended) A method for making a thin silicon structure comprising the steps of:
- providing a glass wafer or substrate;
 - providing a silicon wafer having a first substantially planar surface and a second substantially planar surface;
 - forming a recess in said glass wafer or silicon wafer first surface;

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